

IN THE CLAIMS:

Please cancel claims 13-20.

Please amend the following claims:

- 1        1. (Amended) A laminate support used in the process of wire bonding a circuit device comprising:
  - 2              a substrate having a first surface; and
  - 3              a wire having a diameter positioned on said first surface of said substrate, said substrate including a closed woven mesh having strands whose separation distance is equal to or less than said diameter of said wire on said first surface of said substrate.
- 1        4. (Amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said woven mesh comprises fiberglass.
- 1        5. (Amended) The laminate support used in the process of wire bonding a circuit device in accordance with claim 1, wherein said woven mesh is between approximately 2.5 and 4.0 mils thick.
- 1        7. (Amended) A laminate support used in the process of wire bonding a circuit device comprising:
  - 2              a substrate having a first surface; and
  - 3              a wire having a thickness positioned on said first surface of said substrate, said substrate including a closed woven mesh having warp and weave strands, whose separation distance is equal to or less than the thickness of said wire on said first surface of said